



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yoshino, et al.

Serial No.: 09/909,013

Filed: 07/19/01

For: Semiconductor Package Insulation Film and Manufacturing Method

Thereof

Docket No.: TI-29448

Examiner: Geyer, S. B.

Art Unit: 2829

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Amendment under 37 CFR 1.116

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

January 28, 2003

Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 10/28/02. They are respectfully submitted as a full and complete response to that Action.

Please amend the specification as follows:

In the Claims:

Please amend the claims as follows:

5. (twice amended) A method for manufacture of an insulation film for providing an insulation substrate for carrying a semiconductor chip of a semiconductor package comprising the steps of:

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